

IPC-4562B

2023 - October

**Metal Foil for Printed
Board Applications**

An international standard developed by IPC

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IPC-4562B

Metal Foil for Printed Board Applications

Developed by the 3-12A Task Group of the Base Materials General Committee (3-10) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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Table of Contents

1	SCOPE	1	3.2.5	Cleanliness	6
1.1	Purpose	1	3.2.6	Pinholes and Porosity.....	6
1.2	Foil Designation.....	1	3.3	Dimensional	6
1.2.1	Specification Sheet Description.....	1	3.3.1	Sheet Length and Width.....	6
1.2.2	Foil Metal	1	3.3.2	Roll Width	6
1.2.3	Foil Type	1	3.3.3	Area Weight.....	6
1.2.4	Foil Grade	1	3.3.3.1	Copper Foil.....	6
1.2.4.1	Foil Grades	2	3.3.4	Thickness.....	7
1.2.4.2	Other Metal Foil Grades	2	3.3.4.1	Copper Foil.....	7
1.2.5	Foil Area Weight	2	3.3.4.1.1	Electrodeposited Foil.....	7
1.2.5.1	Copper Foil Area Weight	2	3.3.4.1.2	Wrought Foil.....	7
1.2.5.2	Thickness of Foils Other than Copper.....	2	3.3.4.2	Other Metallic Foil.....	7
1.2.6	Bond Enhancement Treatment The bond enhancement treatment used on the metal foil shall be designated as one of the following:	3	3.3.4.2	Other Metallic Foil.....	7
1.2.7	Foil Profile.....	3	3.3.5	Foil Iron	7
1.3	Quality/Performance Classification.....	3	3.4	Physical Requirements.....	8
1.4	Measurement Units	3	3.4.1	Tensile Strength.....	8
1.5	Definition of Requirements	4	3.4.2	Fatigue Ductility.....	8
1.6	Process Control Requirements.....	4	3.4.3	Elongation	8
1.7	Order of Precedence	4	3.4.4	Peel Strength	8
1.7.1	Conflict	4	3.4.5	Carrier Release Strength	8
1.8	Appendices.....	4	3.5	Processing Requirements.....	8
1.8.1	Appendix A	4	3.5.1	Etchability	8
1.9	Terms and Definitions.....	4	3.5.2	Chemical Cleaning.....	8
1.9.1	AABUS (As Agreed Upon between User and Supplier).....	4	3.5.3	Solderability	8
1.9.2	Profile Factor	4	3.5.4	Treatment Integrity.....	8
2	APPLICABLE DOCUMENTS	4	3.6	Workmanship	8
3	REQUIREMENTS	5	3.7	Requirements for Specific Metal Foil.....	8
3.1	General Requirements Acceptability.....	5	3.7.1	Copper Foil.....	8
3.1.1	Sheet Material	5	3.7.1.1	Purity	8
3.1.2	Roll Material	5	3.7.1.2	Resistivity.....	9
3.2	Visual.....	6	3.7.2	Nickel	9
3.2.1	Pits and Dents.....	6	4	QUALITY ASSURANCE PROVISIONS	9
3.2.2	Wrinkles	6	4.1	Statistical Process Control (SPC)	9
3.2.3	Scratches.....	6	4.2	Responsibility for Inspection	9
3.2.4	Holes and Tears	6	4.2.1	Test Equipment and Inspection Facilities.....	9
			4.2.2	Preparation of Samples	9
			4.2.3	Standard Laboratory Conditions.....	9

4.2.3.1	Permissible Temperature Variation in Environmental Chambers.....	9	4.6.3	Thickness.....	13
4.2.3.2	Reference Conditions.....	10	4.6.3.1	Thickness of Foil.....	13
4.2.4	Tolerances.....	10	4.6.3.2	Area Weight of Foils.....	13
4.3	Classification of Inspections.....	10	4.6.3.2.1	Foil with Releasable Carrier.....	13
4.4	Qualification Inspection.....	10	4.6.3.2.2	Foil with Etchable Carrier.....	13
4.4.1	Frequency.....	10	4.6.3.3	Foil Profile.....	13
4.4.2	Inspection of Product for Delivery.....	10	4.6.4	Tensile Strength.....	13
4.4.3	Extent of Qualification.....	10	4.6.5	Fatigue Ductility.....	13
4.5	Quality Conformance Inspection.....	10	4.6.6	Elongation.....	13
4.5.1	Quality Conformance Inspection.....	10	4.6.7	Peel Strength.....	13
4.5.1.1	Inspection Frequencies.....	10	4.6.7.1	Peel Strength of Thin Foil with Carrier.....	13
4.5.1.2	Lot.....	10	4.6.8	Release Between Carrier and Foil.....	13
4.5.1.3	Lot Size.....	10	4.6.10	Etchability.....	14
4.5.1.4	Unit Size.....	10	4.6.11	Chemical Cleaning.....	14
4.5.2	Sampling Plan.....	10	4.6.12	Solderability.....	14
4.5.3	Sample Unit.....	10	4.6.13	Treatment Integrity.....	14
4.5.4	Group A Inspection.....	10	4.6.14	Purity.....	14
4.5.4.1	Sampling Plans for Class 3 Material.....	10	4.6.15	Resistivity.....	14
4.5.4.2	Sampling Plans for Class 2 Material.....	11	4.7	Statistical Process Control (SPC).....	14
4.5.4.3	Sampling Plan for Class 1 Material.....	12	5 PREPARATION FOR DELIVERY.....	15	
4.5.4.4	Rejected Lots.....	12	5.1	Splices.....	15
4.5.5	Group B Inspection.....	12	5.2	Wrapping.....	15
4.5.5.1	Noncompliance Group B.....	12	5.3	Marking.....	15
4.5.6	Group C Inspection.....	12	5.4	Certificate of Conformance.....	15
4.5.6.1	Noncompliance Group C.....	12	6 NOTES.....	15	
4.6	Test Methods.....	12	6.1	Ordering Data.....	15
4.6.1	Visual.....	12	APPENDIX A Abbreviations and Acronyms.....	28	
4.6.1.1	Pinhole Evaluation of Foils with Carriers.....	12			
4.6.1.2	Pinhole and Porosity Evaluation.....	12			
4.6.2	Dimensions.....	12			

Tables		Tech Sheets
Table 1-1	Metal Foil Material of Construction Designation 1	IPC-4562B – SPECIFICATION SHEET / 01 17 IPC-4562B – SPECIFICATION SHEET / 02 18
Table 1-2	Metal Foil Manufacturing Process Designation 1	IPC-4562B – SPECIFICATION SHEET / 03 19
Table 1-3	Metal Foil Grade Designation 2	IPC-4562B – SPECIFICATION SHEET / 05 20
Table 1-4	Unsupported Metal Foil Designation and Common Industry Term 2	IPC-4562B – SPECIFICATION SHEET / 06 21 IPC-4562B – SPECIFICATION SHEET / 07 22
Table 1-5	Metal Foil Bond Enhancement and Stain Proofing Designation 3	IPC-4562B – SPECIFICATION SHEET / 08 23 IPC-4562B – SPECIFICATION SHEET / 09 24
Table 1-6	Metal Foil Profile Designation 3	IPC-4562B – SPECIFICATION SHEET / 10 25
Table 3-1	Copper Foil Area Weights and Calculated Thickness 6	IPC-4562B – SPECIFICATION SHEET / 11 26
Table 3-2	Maximum Foil Profile 8	
Table 3-3	Maximum Resistivity of Electrodeposited Copper Foil (All Types) 9	
Table 3-4	Maximum Resistivity for Wrought Copper Foil (All Weights) 9	
Table 4-1	Quality Conformance Inspection 11	
Table 4-2	IPC-4562 Sampling Plans 11	
Table 4-3	Lot Inspection Plan 12	

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Metal Foil for Printed Board Applications

1 SCOPE

This specification covers metal unsupported foils and foils supported by carrier films suitable for subsequent use in printed boards. Unless otherwise agreed upon between user and supplier (AABUS), metal foils **shall** be considered acceptable, so long as the requirements in this specification are met.

1.1 Purpose This specification addresses the requirements for procurement of metal foils used only in printed wiring applications.

1.2 Foil Designation The foil designation **shall** be in the following forms:

IPC-4562/XX	Where XX is the specification sheet number (See 1.2.1)
CU	Foil Metal (See 1.2.2)
E	Foil Type (See 1.2.3)
3	Foil Grade (See 1.2.4)
2	Foil Thickness (See 1.2.5)
S	Bond Enhancement Treatment (See 1.2.6)
XS	Foil Profile (See 1.2.7)
3	Quality Classification (See 1.3)

Example: IPC-4562/03-CUSE32SXS3

1.2.1 Specification Sheet Description At the end of this document is a series of specification sheets. Each sheet outlines engineering and performance data for a metal foil. The sheets are provided with a number for ordering purposes. For example, if a user wishes to order from specification sheet 1, the number “1” would be substituted for the “X” in the above designation example (e.g., IPC-4562/1).

The metal foils contained in this standard represent known materials. As new foils become available, they may be added to future revisions. Users and material developers are encouraged to supply information on new materials for review by the Metallic Foils Task Group (3-12a). Users who wish to invoke this specification for metal foils not listed **shall** list a 00 (zero zero) for the specification sheet number (e.g., IPC-4562/00).

This specification provides quality classes (see 1.3) for requirements to reflect functional performance. The reference of a single class does not preclude invoking specific requirements defined in other classes.

1.2.2 Foil Metal The metal foil **shall** be designated by a suitable two- or three-letter code:

Table 1-1: Metal Foil Material of Construction Designation

Designation	Materials of Construction
CU	Copper
NI	Nickel
XX	Other

1.2.3 Foil Type Metal foil types **shall** be distinguished by their process of manufacture and **shall** be designated as:

Table 1-2: Metal Foil Manufacturing Process Designation

Designation	Manufacturing Process
E	Electrodeposited
W	Wrought (rolled)
O	Other

1.2.4 Foil Grade Foil grade is a designation of the metal type, method of manufacture, and desired mechanical properties. The details of the designations can be found on the specification sheets at the end of this standard.